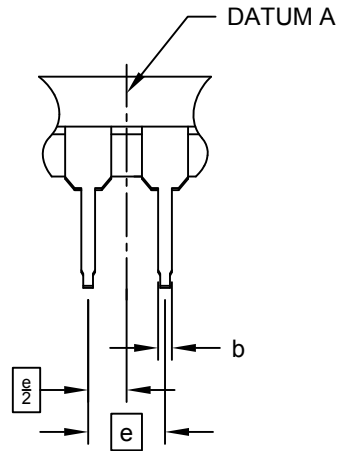
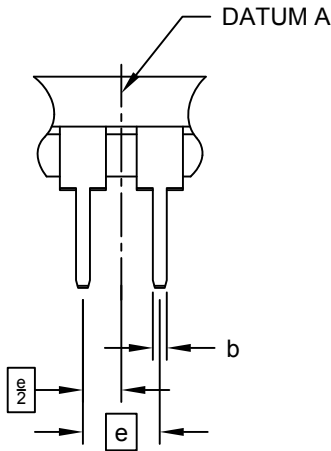


8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

ALTERNATE LEAD DESIGN (NOTE 5)



		Units	INCHES		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		.100 BSC		
Top to Seating Plane	A	-	-		.210
Molded Package Thickness	A2	.115	.130		.195
Base to Seating Plane	A1	.015	-		-
Shoulder to Shoulder Width	E	.290	.310		.325
Molded Package Width	E1	.240	.250		.280
Overall Length	D	.348	.365		.400
Tip to Seating Plane	L	.115	.130		.150
Lead Thickness	c	.008	.010		.015
Upper Lead Width	b1	.040	.060		.070
Lower Lead Width	b	.014	.018		.022
Overall Row Spacing	§	eB	-	-	.430

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- Lead design above seating plane may vary, based on assembly vendor.